

65.00mm

41.00mm

DOH MB v2.1.1 - 0.5mm, 4-layer Board

Material Selection

Halogen-free FR-4
Permittivity @ 100MHz:
Permittivity @ 1GHz:
Loss Tangent @ 100MHz:
Loss Tangent @ 1GHz:
Lead Free Assembly Compatible

Solder resist colour: green
Silkscreen print colour: white

Surface Finish

On top and bottom layer surfaces:
electroless nickel immersion gold

Holes / Drilling

Drill files contain finished hole diameters
Drilling layer pairs: 1-4

Board Outline

Contour routed with break-away tabs

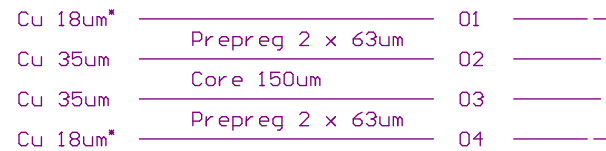
Element Counts (for reference only)

Components: 104
Nets: 110
Pads: 611
Tracks: 2962
Polygons: 0
Holes: 321
Vias: 297

Non-standard Tolerances

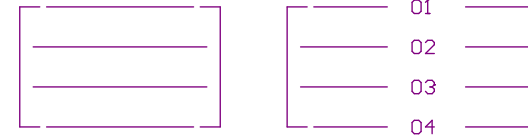
Holes sized 0.2mm and 0.3mm may be plugged by plating. These are all vias.
For them we do not care the finished hole sizes.

Board Layer Stack



*35um final after plating
Total Laminated Thickness: 0.5mm +/- 0.05mm

Drill Layer-Pairs



Layer Name	Gerber
Top Paste Mask	.gtp
Top Overlay	.gto
Top Solder Mask	.gts
Top Layer	.gtl
Plane 1 <PWR>	.gp1
Plane 2 <GND>	.gp2
Bottom Layer	.gbl
Bottom Solder Mask	.gbs
Bottom Overlay	.gbo
Bottom Paste Mask	.gbp
Board Outline	.gm1

Controlled Impedance Reference

Diff. trace width/space on top and bottom layer (microstrip) 100 ohms D10% : 0.1/0.1mm
Diff. trace width/space on top and bottom layer (microstrip) 75 ohms D10% : 0.2/0.1mm